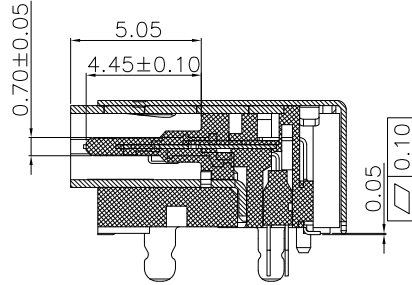
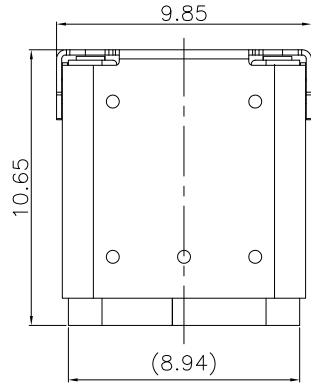
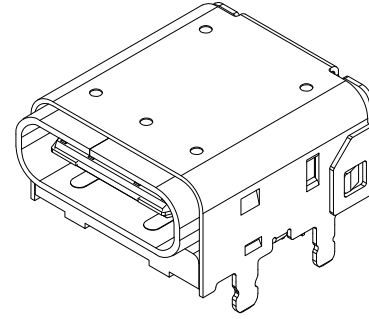


HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	22-02-18
A1	ECN220401001	A1, A12, B1, B12改为开路	HL.W	BENDEE	BENDEE	22-06-06



SECTION A-A
SCALE 1:1



料号备注

CT 3 F 206 M XX R XX XX

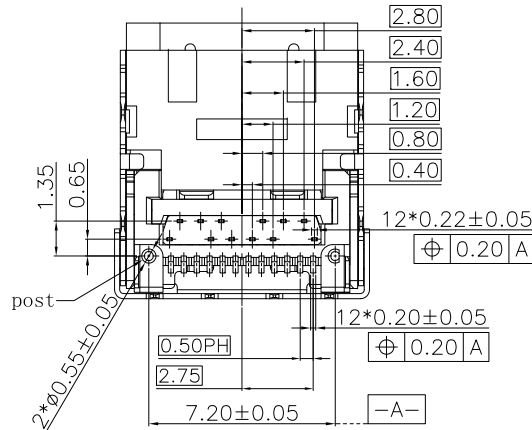
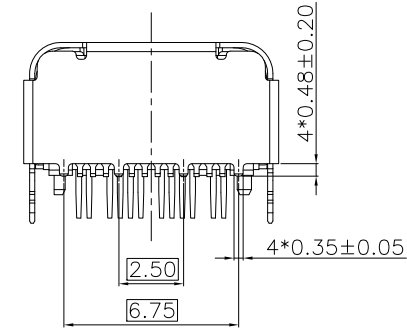
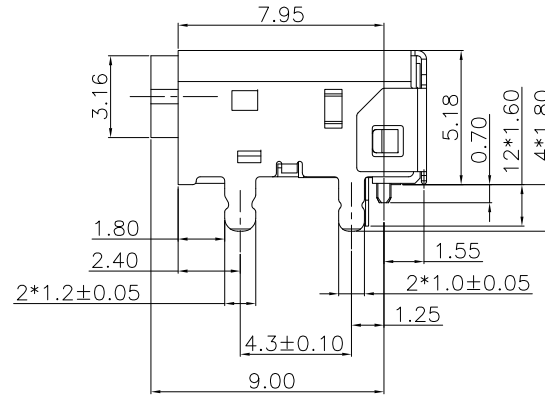
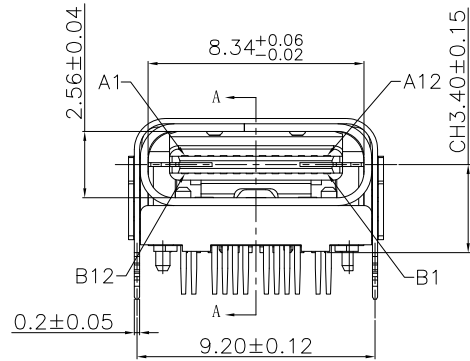
R=PACK-R0213

12=半金雾锡1U"
13=半金雾锡3U"
14=半金雾锡5U"
15=半金雾锡15U"
16=半金雾锡30U"

00=LCP黑不锈钢壳镀镍

R=ROHS2.0标准
W=无卤+ROHS2.0

B=盐雾24H
C=盐雾48H



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Dong Guan XingKeJieXin Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED
TOLERANCES

METRIC
X. +/- 0.38
.X +/- 0.25
.XX +/- 0.15
FRACTIONS +/-
ANGLES +/- 2.00°

DIMENSIONS
(METRIC) (MM)

APPROVAL

制图 HL.W

审核

核准

文件位置

ANGLE OF PROJECTION

第一角画法

比例

日期

2022.06.06

品名

规格

料号

字张

A4

比例

USB 3.1 GEN2 TYPE C RECEPTACLE 24P
SMT+DIP CH3.4 L10.65[脚距4.3]

SEE TABLE

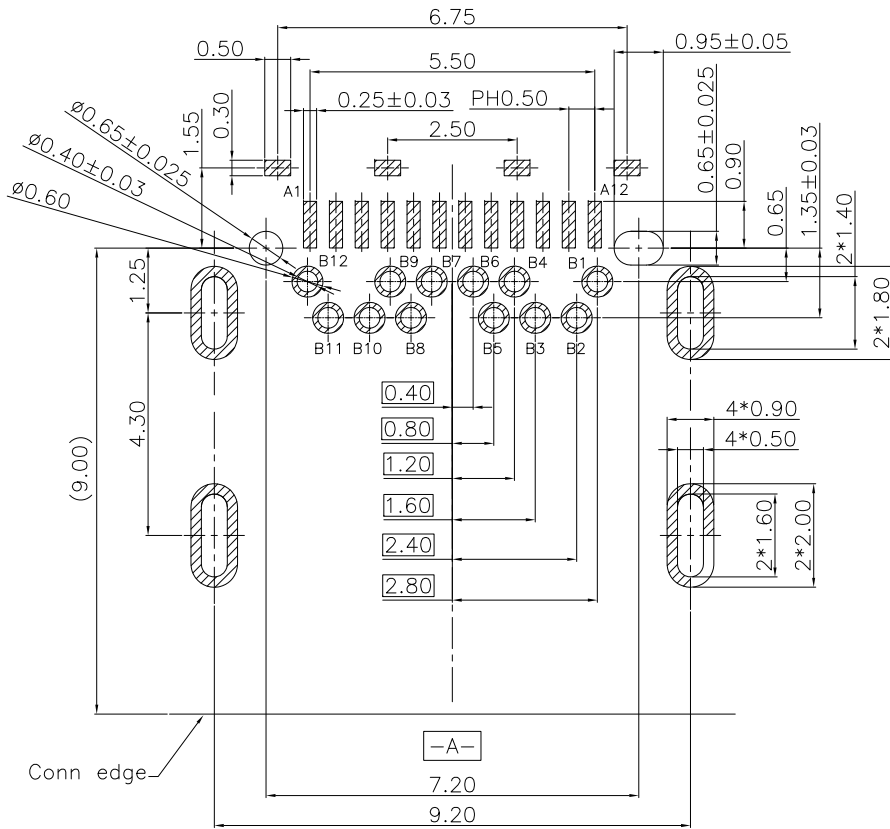
工程图号: DWG-CTCF-206

版本: A1

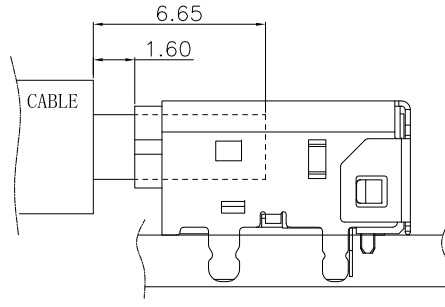
状态码 A 页数 1 OF 2

HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	22-02-18
A1	ECN220401001	A1, A12, B1, B12改为开路	HL.W	BENDEE	BENDEE	22-06-06



RECOMMENDED PCB LAYOUT(TOP) SCALE 2:1
TOLERANCES:±0.05MM



Mating

料号备注									
CT	3	F	206	M	X	X	R	X	X
R=PACK-R0213									
12=半金雾锡10u									
13=半金雾锡30u									
14=半金雾锡50u									
15=半金雾锡150u									
16=半金雾锡300u									
00=LCP黑不锈钢壳镀镍									
R=ROHS2.0标准									
W=无卤+ROHS2.0									
B=盐雾24H									
C=盐雾48H									

Specifications:

- 1.0 Electrical performance:
- 1.1 Contact resistance: 40mΩ max for initial. 10mΩ change after test. measure at 20mv, 100mA.
- 1.2 Dielectric withstanding voltage:AC 100V(rms).
- 1.3 Insulation resistance:100MΩ min.
- 1.4 Contact current rating:
3A for Vbus pin;1.25A for Vconn and GND pin;0.25A for all the other pin.
- 1.5 Voltage: 5 Vac (rms).
- 2.0 mechanical performance:
- 2.1 Mating force:5~20N
- 2.2 Unmating force:8~20N Initial test, 6~20N After test
- 2.3 Durability:10,000 cycles.
- 3.0 Environmental performance:
- 3.1 Temperature range:
- 3.2 Operating temperature:−25°to+85°.
- 3.3 Storage temperature:−20°to+60°.
- 4.0 Material:
- 4.1 Housing:LCP E130i Black,UL94−V0,HF
- 4.2 Contact:C7025,T=0.12mm
- 4.3 Mid-plate: SUS301,T=0.15mm
- 4.4 Shell-in:SUS304 T=0.30mm
- 4.5 Shell-out:SUS301 T=0.20mm
- 5.0 Plating specification:
- 5.1 Contact:Au(see table) plated on contact area Matte Tin plated 100u"min on solder area;Nickel 50u"min underplating over all.
- 5.2 Shell-out:Nickel 30u"min plating over all.

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME



东莞市兴科杰鑫电子有限公司
Dong Guan XingKeJieXin Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES	
X.	+/-
.X	+/-
.XX	+/-
FRACTIONS	+/-
ANGLES	+/-
DIMENSIONS	
(METRIC)	(MM)

APPROVAL		日期	品名
制图	HL.W	2022.06.06	规格
审核			
核准			
文件位置		料号	
ANGLE OF PROJECTION		字张	工程图号:
		A4	DWG-CTCF-206
		比例	1 : 1

USB 3.1 GEN2 TYPE C RECEPTACLE 24P SMT+DIP CH3.4 L10.65[脚距4.3]			
SEE TABLE			
版本: A1			
状态码	A	页数	2 OF 2